RELIABILITY REPORT

FOR

MAX8211xxx

PLASTIC ENCAPSULATED DEVICES

May 24, 2003

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Written by

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Conclusion

The MAX8211 successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

Table of Contents

I. Device Description

A. General

Maxim's MAX8211 is a CMOS micropower voltage detector that warns microprocessors (µPs) of power failures. The MAX8211 contains a comparator, a 1.15V bandgap reference, and open drain N-channel output driver. Two external resistors are used in conjunction with the internal reference to set the trip voltage to the desired level. A Hysteresis output is also included, allowing the user to apply positive feedback for noise-free output switching.

The MAX8211 provides a 7mA current-limited output sink whenever the voltage applied to the threshold pin is less than the 1.5V internal reference.

The CMOS MAX8211 is a plug-in replacements for the bipolar ICL8211 in applications where the maximum supply voltage is less than 16.5V. It offera several performance advantages, including reduced supply current, a more tightly controlled bandgap reference, and more available current from the hysteresis output.

B. Absolute Maximum Ratings

Item	Rating
Supply Voltage	-0.5V to +18V
Output Voltage	-0.5V to +18V
Hysteresis	+0.5V to -18V with respect to (V+ + 0.5V)
Threshold Input Voltage	-0.5V to (V+ + 0.5V)
Current into Any Terminal	±50mA
Operating Temperature Ranges	
MAX8212C_ _	0°C to +70°C
MAX8212E_ _	-40°C to +85°C
Storage Temperature Range	-65°C to +150°C
Lead Temperature (soldering, 10sec)	+300°C
Continuous Power Dissipation (TA = +70°C)	
8-Pin PDIP	727mW
8-Pin SO	471mW
8-Pin uMAX	330mW
Derates above +70°C	
8-Pin PDIP	9.09mW/°C
8-Pin SO	5.88mW/°C
8-Pin uMAX	4.1mW/°C

II. Manufacturing Information

A. Description/Function:	Programmable Voltage Detector
B. Process:	SMG (M6--6 micron metal gate CMOS)
C. Number of Device Transistors:	30
D. Fabrication Location:	Oregon, USA
E. Assembly Location:	Philippines, Malaysia, or Thailand
F. Date of Initial Production:	November, 1993

III. Packaging Information

A. Package Type:	**8-Lead Plastic Dip**	**8-Lead SO**	**8-Lead uMAX**
B. Lead Frame:	Copper	Copper	Copper
C. Lead Finish:	Solder Plate	Solder Plate	Solder Plate
D. Die Attach:	Silver-filled Epoxy	Silver-filled Epoxy	Silver-filled Epoxy
E. Bondwire:	Gold (1.3 mil dia.)	Gold (1.0 mil dia.)	Gold (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler	Epoxy with silica filler	Epoxy with silica filler
G. Assembly Diagram:	# 05-0701-0296	# 05-0701-0297	# 05-0701-0764
H. Flammability Rating:	Class UL94-V0	Class UL94-V0	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard JESD22-112:	Level 1	Level 1	Level 1

IV. Die Information

A. Dimensions:	57 x 69 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Aluminum/Si (Si = 1%)
D. Backside Metallization:	None
E. Minimum Metal Width:	6 microns (as drawn)
F. Minimum Metal Spacing:	6 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts: Jim Pedicord (Manager, Reliability Operations)
Bryan Preeshl (Executive Director**)**
Kenneth Huening (Vice President)

B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.

C. Observed Outgoing Defect Rate: < 50 ppm

D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in **Table 1**. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4389 \times 400 \times 2}$$

(Chi square value for MTTF upper limit)

Temperature Acceleration factor assuming an activation energy of 0.8eV

$\lambda = 2.71 \times 10^{-9}$

$\lambda = 2.71$ F.I.T. (60% confidence level @ 25°C)

This low failure rate represents data collected from Maxim's reliability monitor program. In addition to routine production Burn-In, Maxim pulls a sample from every fabrication process three times per week and subjects it to an extended Burn-In prior to shipment to ensure its reliability. The reliability control level for each lot to be shipped as standard product is 59 F.I.T. at a 60% confidence level, which equates to 3 failures in an 80 piece sample. Maxim performs failure analysis on any lot that exceeds this reliability control level. Attached Burn-In Schematic (Spec. # 06-1797) shows the static Burn-In circuit. Maxim also performs quarterly 1000 hour life test monitors. This data is published in the Product Reliability Report (**RR-1M**).

B. Moisture Resistance Tests

Maxim pulls pressure pot samples from every assembly process three times per week. Each lot sample must meet an LTPD = 20 or less before shipment as standard product. Additionally, the industry standard 85°C/85%RH testing is done per generic device/package family once a quarter.

C. E.S.D. and Latch-Up Testing

The PS50 die type has been found to have all pins able to withstand a transient pulse of ±600V per Mil-Std-883 Method 3015 (reference attached ESD Test Circuit). Latch-Up testing has shown that this device withstands a current of ±100mA.

Table 1
Reliability Evaluation Test Results

MAX8211xxx

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	PACKAGE	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)					
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality		400	0
Moisture Testing (Note 2)					
Pressure Pot	Ta = 121°C P = 15 psi. RH= 100% Time = 168hrs.	DC Parameters & functionality	PDIP SO uMAX	77 77 77	0 0 0
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality		77	0
Mechanical Stress (Note 2)					
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality		77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Package/Process data

Attachment #1

TABLE II. Pin combination to be tested. 1/ 2/

	Terminal A (Each pin individually connected to terminal A with the other floating)	Terminal B (The common combination of all like-named pins connected to terminal B)
1.	All pins except V_{PS1} 3/	All V_{PS1} pins
2.	All input and output pins	All other input-output pins

1/ Table II is restated in narrative form in 3.4 below.
2/ No connects are not to be tested.
3/ Repeat pin combination I for each named Power supply and for ground

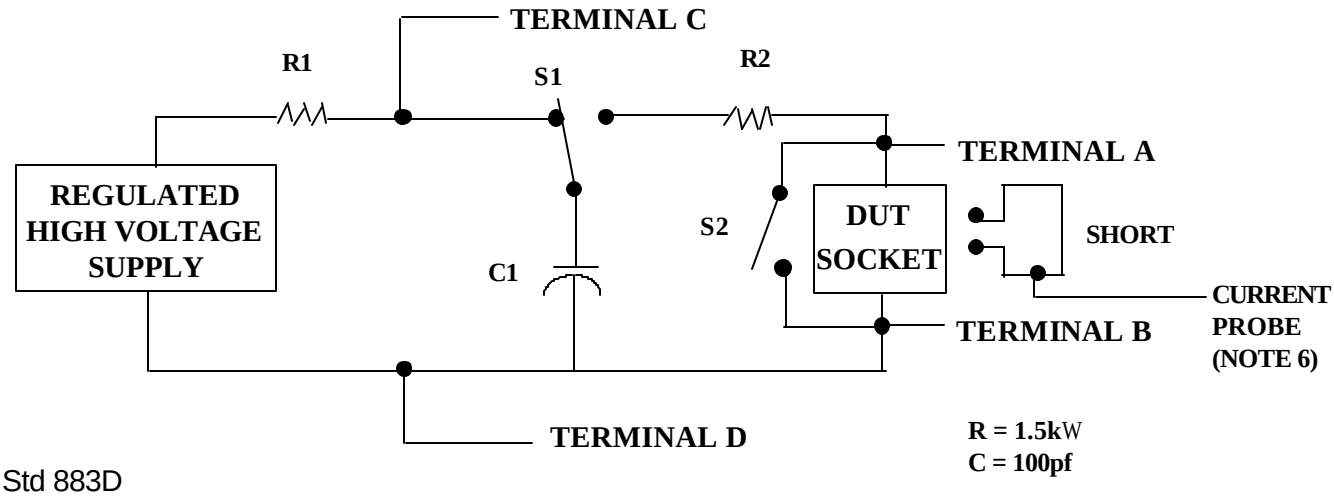
(e.g., where V_{PS1} is V_{DD}, V_{CC}, V_{SS}, V_{BB}, GND, $+V_S$, $-V_S$, V_{REF}, etc).

3.4 Pin combinations to be tested.

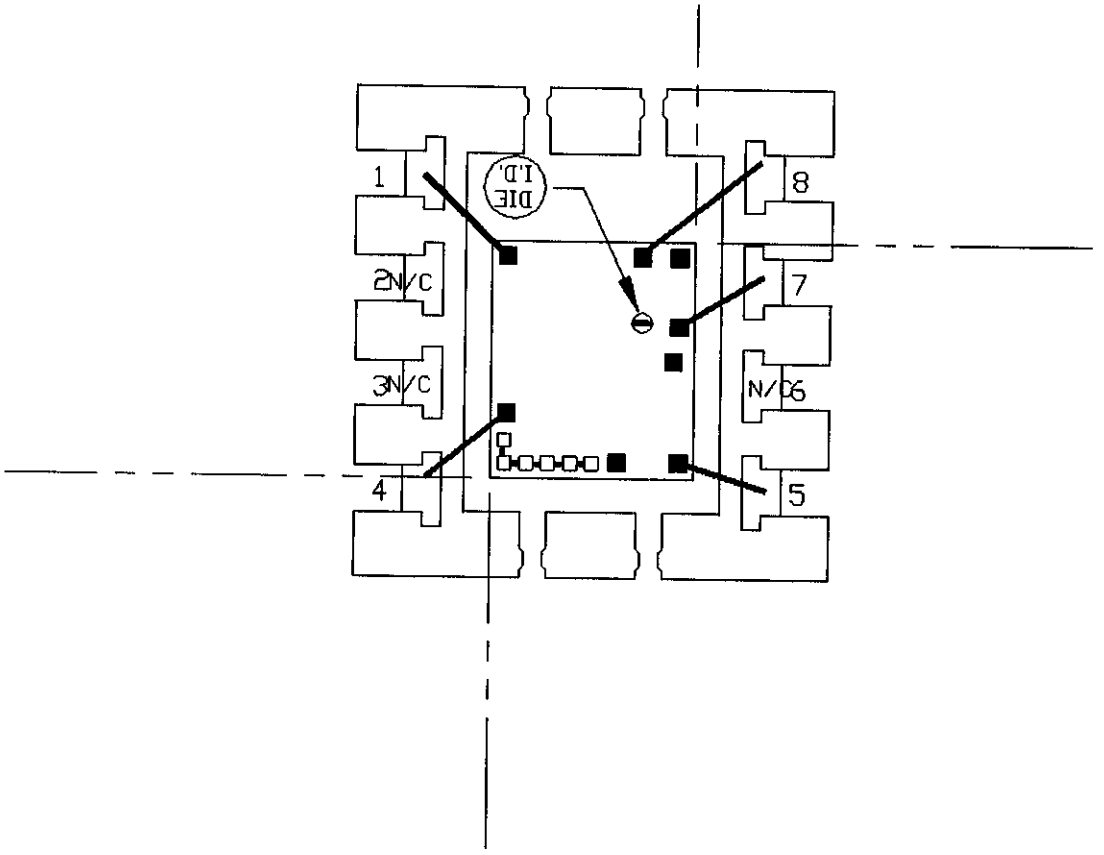
a. Each pin individually connected to terminal A with respect to the device ground pin(s) connected to terminal B. All pins except the one being tested and the ground pin(s) shall be open.

b. Each pin individually connected to terminal A with respect to each different set of a combination of all named power supply pins (e.g., V_{SS1}, or V_{SS2} or V_{SS3} or V_{CC1}, or V_{CC2}) connected to terminal B. All pins except the one being tested and the power supply pin or set of pins shall be open.

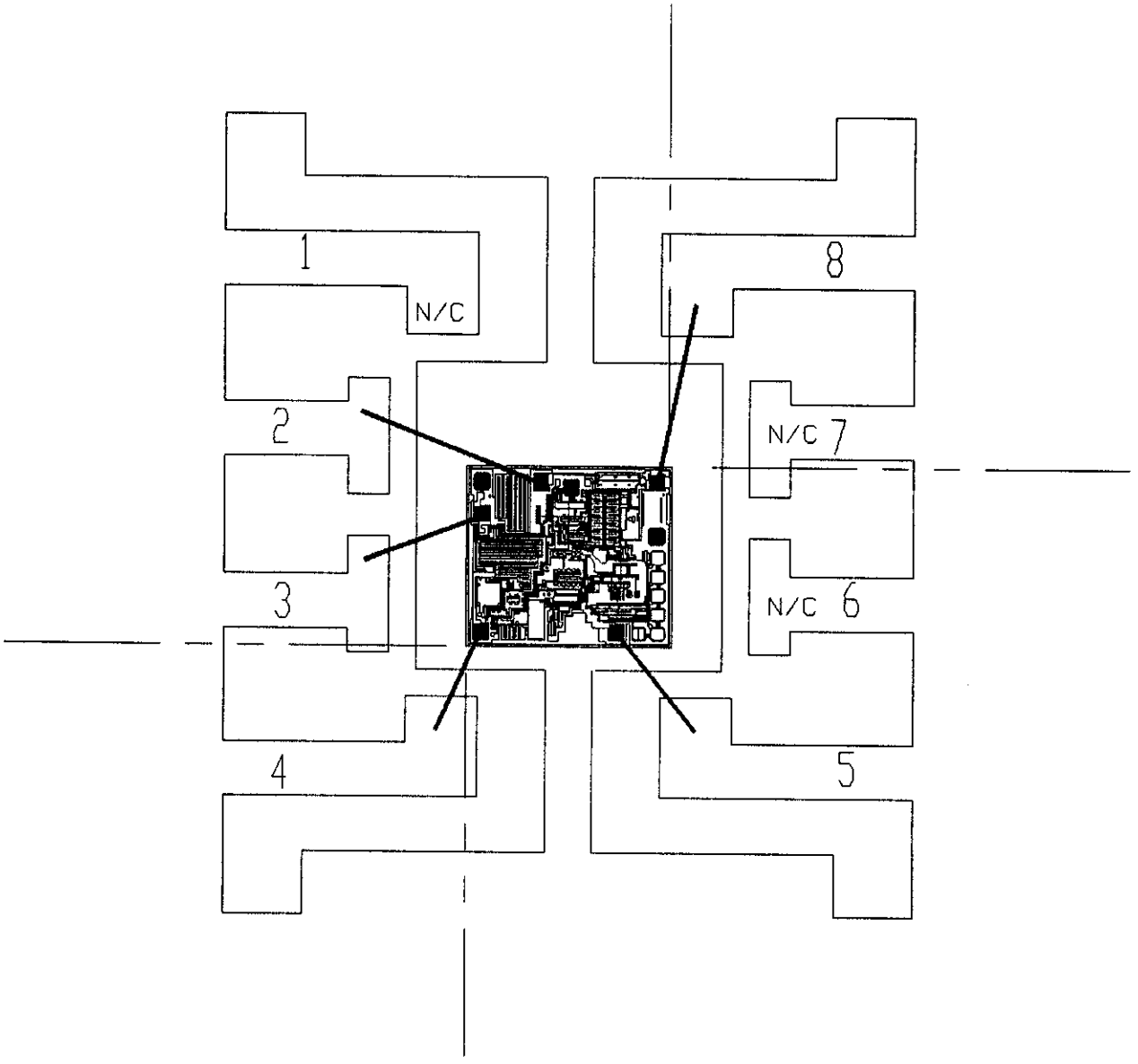
c. Each input and each output individually connected to terminal A with respect to a combination of all the other input and output pins connected to terminal B. All pins except the input or output pin being tested and the combination of all the other input and output pins shall be open.



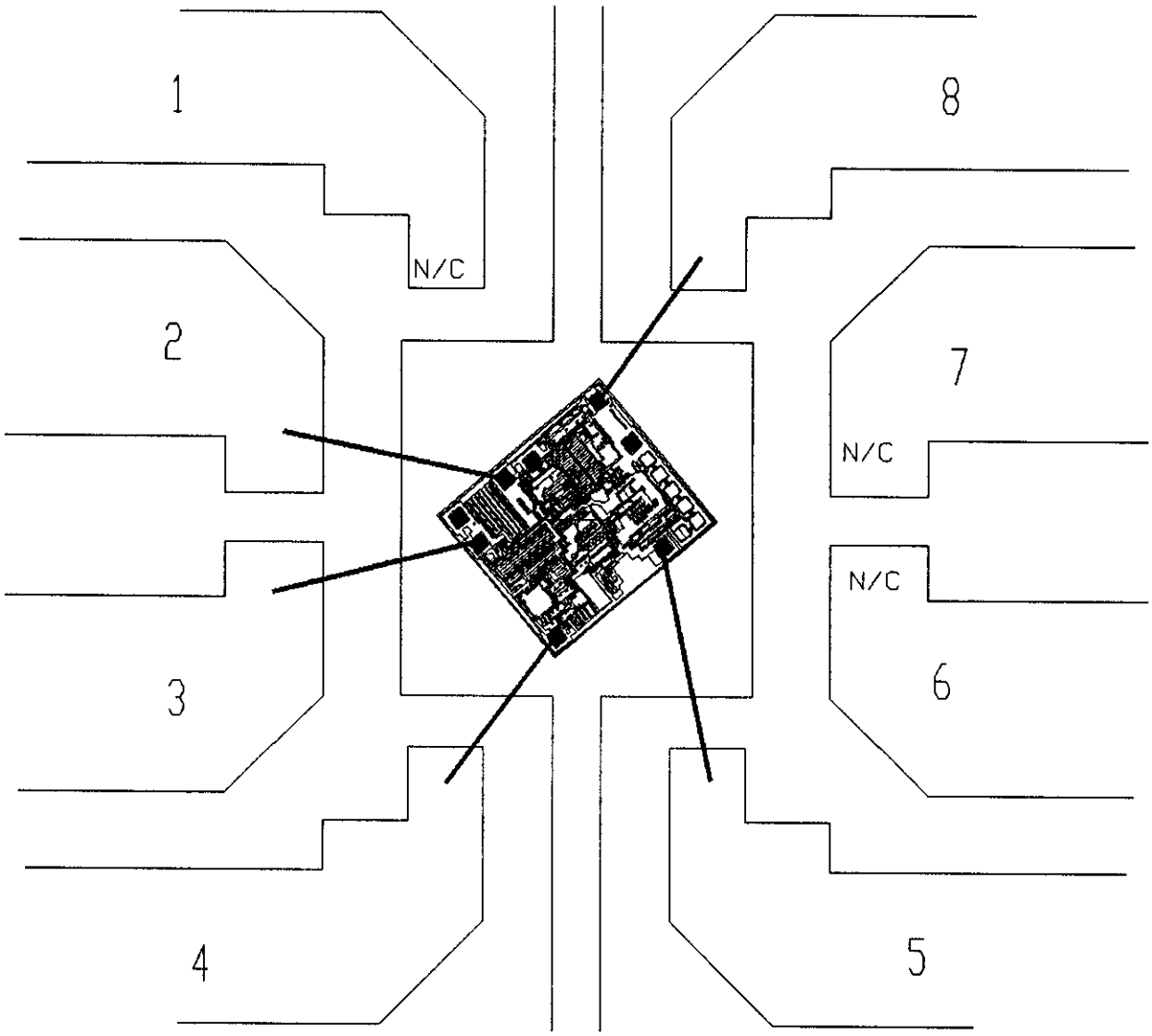
Mil Std 883D
Method 3015.7
Notice 8



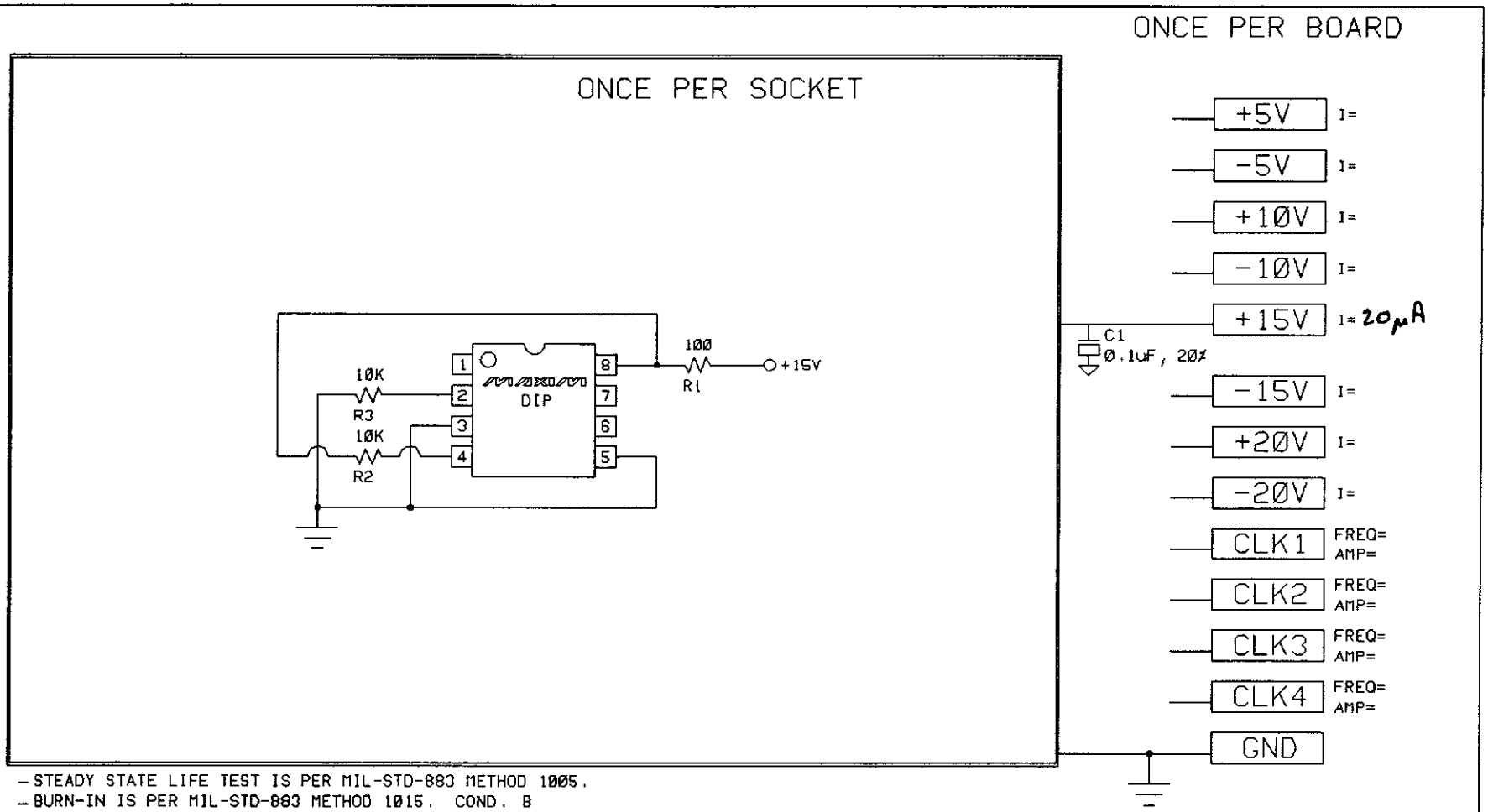
PKG.CODE: U8-1		APPROVALS	DATE	MAXIM
CAV./PAD SIZE: 68X94	PKG. DESIGN			BUILDSHEET NUMBER: 05-0701-0764 / REV.: A



PKG.CODE: S8-2		✓ APPROVALS	DATE	MAXIM
CAV./PAD SIZE: 90 X 90	PKG. DESIGN			BUILDSHEET NUMBER: 05-0701-0297 / REV.: B



PKG.CODE: P8-1		APPROVALS	DATE	MAXIM
CAV./PAD SIZE: 100 X 100	PKG. DESIGN			BUILDSHEET NUMBER: 05-0701-0296 REV.: A



- STEADY STATE LIFE TEST IS PER MIL-STD-883 METHOD 1005.
- BURN-IN IS PER MIL-STD-883 METHOD 1015. COND. B

NOTES:

1. TEMPERATURE: 125C OR EQUIVALENT
2. TIME: 160 HOURS MIN. OR EQUIVALENT
3. ALL COMPONENTS AND MATERIAL MUST STAND 150C CONTINUOUS
4. APPROVED FOR [X] COMMERCIAL
   [X] HR/883

SPEC. NO. 06-1797 REV. A

DATE: 6/25/92

DRAWN BY: N.K. NGUYEN

MAXIM BURN-IN SCHEMATIC

DEVICE TYPE:

MAX8211/2